

- 2 A Continuous On-State Current
- 15 A Surge-Current
- Glass Passivated Wafer
- 400 V to 600 V Off-State Voltage
- Max I_{GT} of 200 μ A
- Package Options

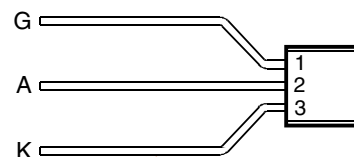
| PACKAGE | PACKING | PART # SUFFIX |
|---------------------|---------------|---------------|
| LP | Bulk | (None) |
| LP with fomed leads | Tape and Reel | R |

**LP PACKAGE
(TOP VIEW)**



MDC1AA

**LP PACKAGE
WITH FORMED LEADS
(TOP VIEW)**



MDC1AB

absolute maximum ratings over operating case temperature (unless otherwise noted)

| RATING | | SYMBOL | VALUE | UNIT |
|------------------------------------------------------------------------------|----------------------|--------------|-------------|------|
| Repetitive peak off-state voltage (see Note 1) | TICP106D TICP106M | V_{DRM} | 400 600 | V |
| Repetitive peak reverse voltage | TICP106D TICP106M | V_{RRM} | 400 600 | V |
| Continuous on-state current at (or below) 25°C case temperature (see Note 2) | | $I_{T(RMS)}$ | 2 | A |
| Surge on-state current (see Note 3) | | I_{TSM} | 15 | A |
| Peak positive gate current (pulse width $\leq 300 \mu$ s) | | I_{GM} | 0.2 | A |
| Average gate power dissipation (see Note 4) | | $P_{G(AV)}$ | 0.3 | W |
| Operating case temperature range | | T_C | -40 to +110 | °C |
| Storage temperature range | | T_{stg} | -40 to +125 | °C |
| Lead temperature 3.2 mm from case for 10 seconds | | T_L | 230 | °C |

- NOTES: 1. These values apply when the gate-cathode resistance $R_{GK} = 1 \text{ k}\Omega$.
2. These values apply for continuous dc operation with resistive load. Above 25°C derate linearly to zero at 110°C.
3. This value applies for one 50 Hz half-sine-wave when the device is operating at (or below) the rated value of peak reverse voltage and on-state current. Surge may be repeated after the device has returned to original thermal equilibrium.
4. This value applies for a maximum averaging time of 20 ms.

PRODUCT INFORMATION

MARCH 1988 - REVISED SEPTEMBER 2002
Specifications are subject to change without notice.

electrical characteristics at 25°C case temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT |
|-----------|-----------------------------------|-------------------------------|--------------------------------------------------------------------------------|-----|-----|-----|---------------|
| I_{DRM} | Repetitive peak off-state current | $V_D = \text{rated } V_{DRM}$ | $R_{GK} = 1 \text{ k}\Omega$ | | | 20 | μA |
| I_{RRM} | Repetitive peak reverse current | $V_R = \text{rated } V_{RRM}$ | $I_G = 0$ | | | 200 | μA |
| I_{GT} | Gate trigger current | $V_{AA} = 12 \text{ V}$ | $R_L = 100 \Omega$ $t_{p(g)} \geq 20 \mu\text{s}$ | | 5 | 200 | μA |
| V_{GT} | Gate trigger voltage | $V_{AA} = 12 \text{ V}$ | $R_L = 100 \Omega$ $R_{GK} = 1 \text{ k}\Omega$ $t_{p(g)} \geq 20 \mu\text{s}$ | 0.4 | | 1 | V |
| I_H | Holding current | $V_{AA} = 12 \text{ V}$ | $R_{GK} = 1 \text{ k}\Omega$ Initiating $I_T = 10 \text{ mA}$ | | | 5 | mA |
| V_T | On-state voltage | $I_T = 1 \text{ A}$ | (see Note 5) | | | 1.5 | V |

NOTE 5: This parameter must be measured using pulse techniques, $t_p = 1 \text{ ms}$, duty cycle $\leq 2 \%$. Voltage sensing-contacts, separate from the current carrying contacts, are located within 3.2 mm from the device body.

OBSELETE

PRODUCT INFORMATION